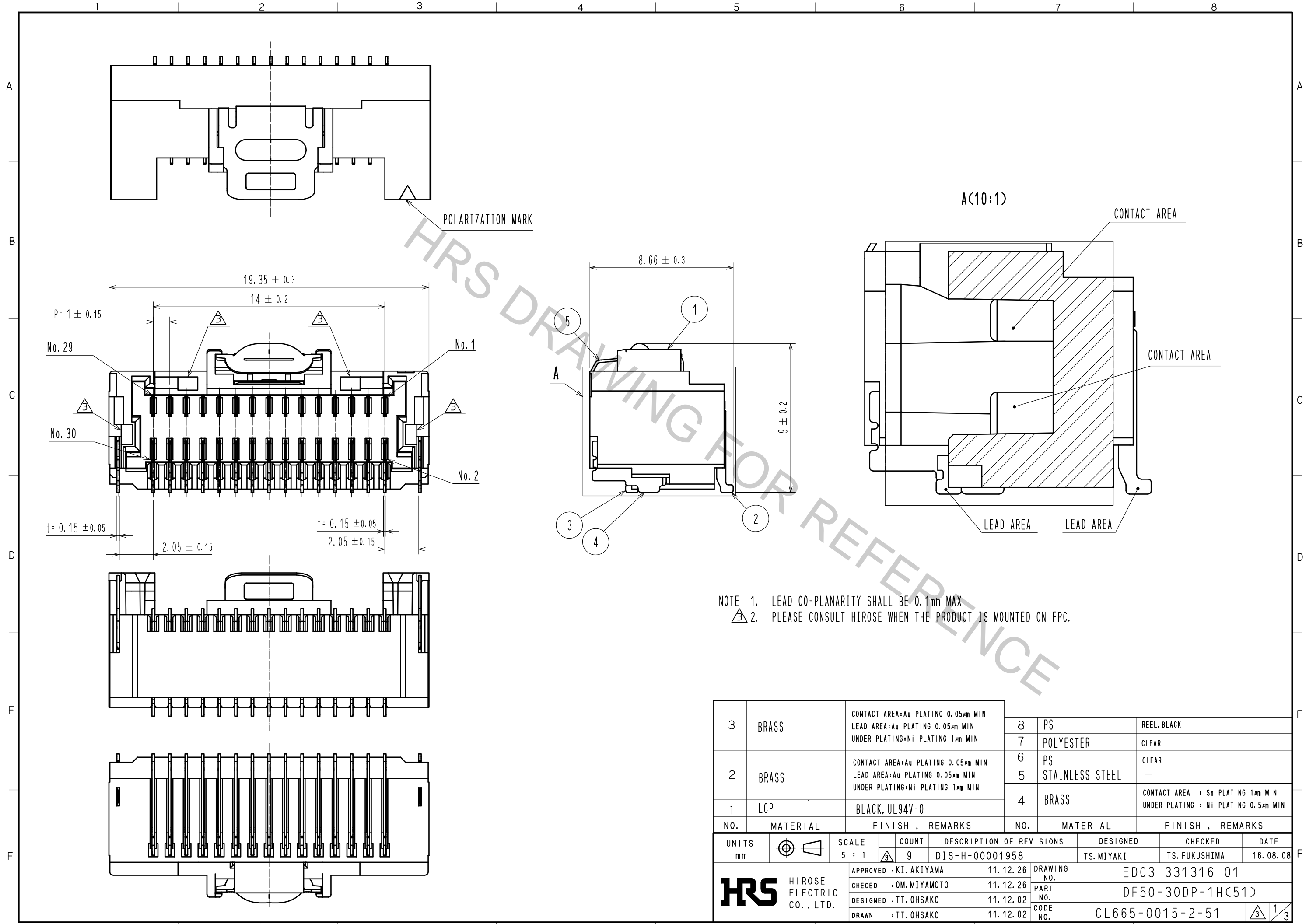


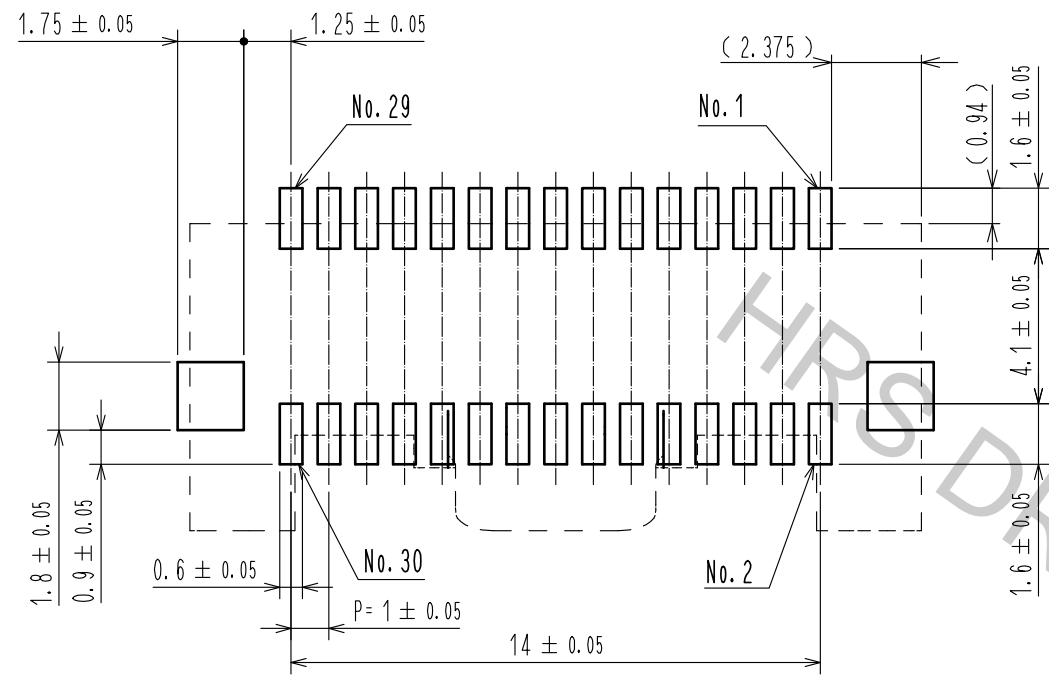
Apr.1.2017 Copyright 2017 HIROSE ELECTRIC CO., LTD. All Rights Reserved.



NOTE 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX  
 2. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED ON FPC.

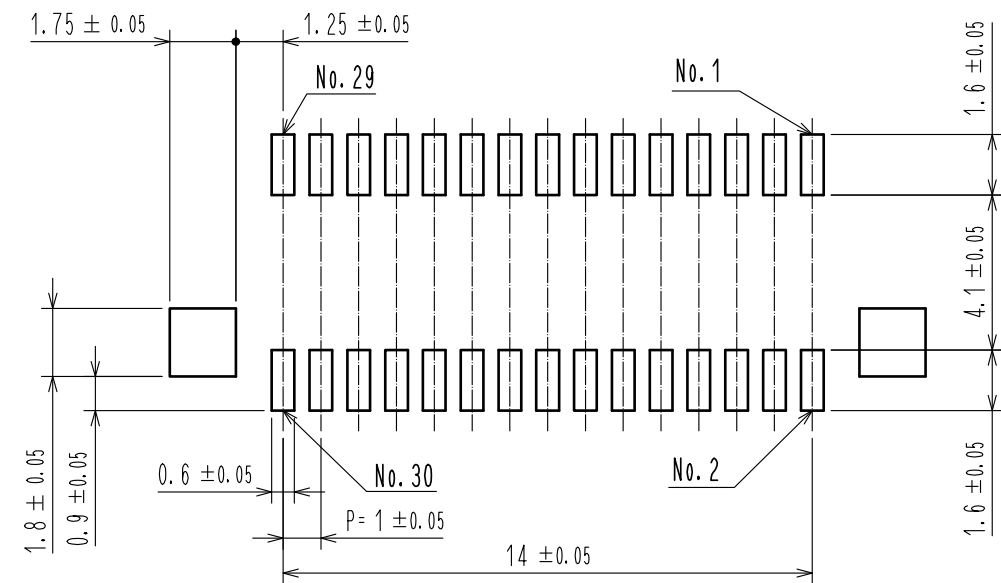
3	BRASS	CONTACT AREA: Au PLATING 0.05µm MIN LEAD AREA: Au PLATING 0.05µm MIN UNDER PLATING: Ni PLATING 1µm MIN	8	PS	REEL BLACK
2	BRASS	CONTACT AREA: Au PLATING 0.05µm MIN LEAD AREA: Au PLATING 0.05µm MIN UNDER PLATING: Ni PLATING 1µm MIN	7	POLYESTER	CLEAR
1	LCP	BLACK, UL94V-0	6	PS	CLEAR
			5	STAINLESS STEEL	—
			4	BRASS	CONTACT AREA : Sn PLATING 1µm MIN UNDER PLATING : Ni PLATING 0.5µm MIN
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE 5 : 1	COUNT 9	DESCRIPTION OF REVISIONS DIS-H-00001958	
DESIGNED TS. MIYAKI		CHECKED TS. FUKUSHIMA		DATE 16.08.08	
APPROVED : KI. AKIYAMA 11.12.26			DRAWING NO. EDC3-331316-01		
CHECKED : OM. MIYAMOTO 11.12.26			PART NO. DF50-30DP-1H(51)		
DESIGNED : TT. OHSAKO 11.12.02			CODE NO. CL665-0015-2-51		
DRAWN : TT. OHSAKO 11.12.02			1/3		

RECOMMENDED PCB LAYOUT  
(MOUNTING SURFACE SIDE) (FREE)

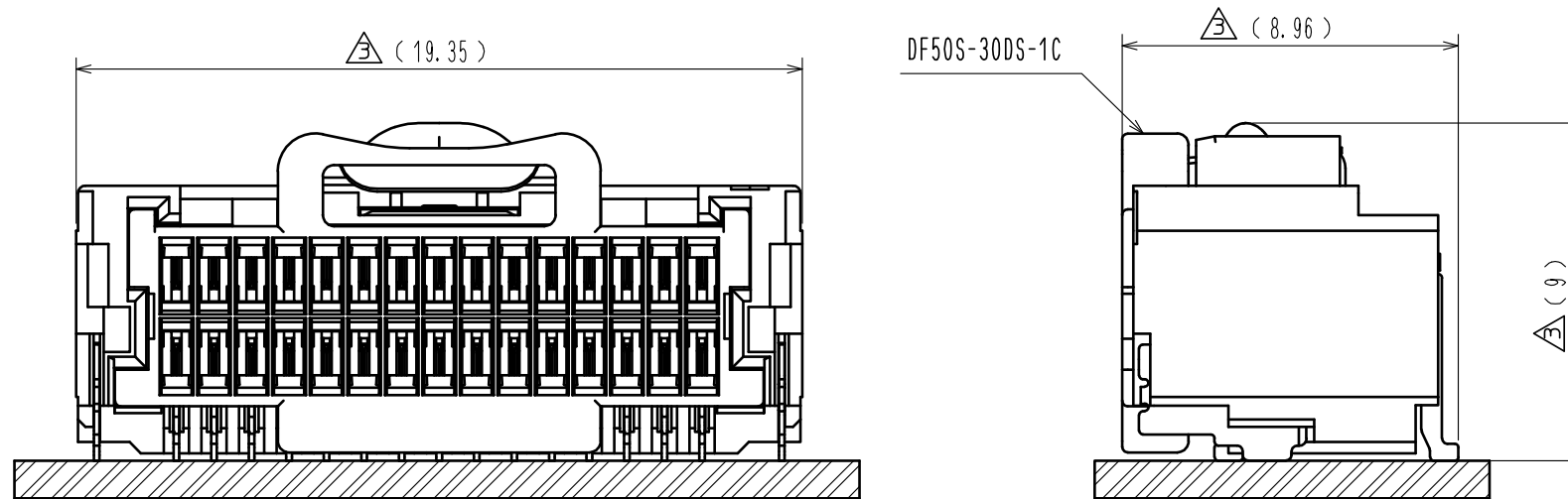


RECOMMENDED METAL MASK (FREE)

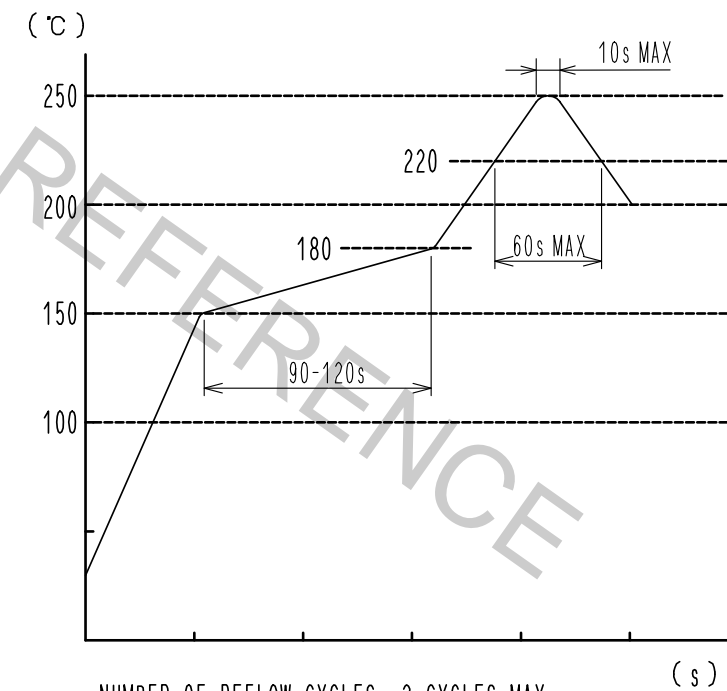
THICKNESS : 0.1mm  
OPEN AREA RATIO:100%



MATING FIGURE (5 : 1)



REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.  
THE TEMPERATURE OF THIS PROFILE IS MEASURED ON THE LEAD TERMINAL.

WE RECOMMEND PERFORMING AN EVALUATION UNDER THE MOUNTING CONDITIONS YOU WILL BE USING BECAUSE IT COULD BE AFFECTED BY ANY CONDITION:TYPE OF SOLDER PASTE, SIZE OF PCB, MOUNTING MATERIAL etc..

<b>HRS</b>	DRAWING NO.	EDC3-331316-01
	PART NO.	DF50-30DP-1H(51)
	CODE NO.	CL665-0015-2-51
		$\triangle$ 2/3

